Company Presentation

May 5, 2015

Infineon and International Rectifier: A Powerful Combination

- As of **January 2015**, International Rectifier is an Infineon Technologies company
- Combined **pro-forma revenue of ~€5,150m*** (~6,950m USD) in Infineon 2014 fiscal year
- About **35,000 employees worldwide*** (as of March 2015)
- Strong technology portfolio with more than **22,800 patents and patent applications** (as of September 2014)
- **33 R&D locations; 20 manufacturing locations**

*non-audited figures

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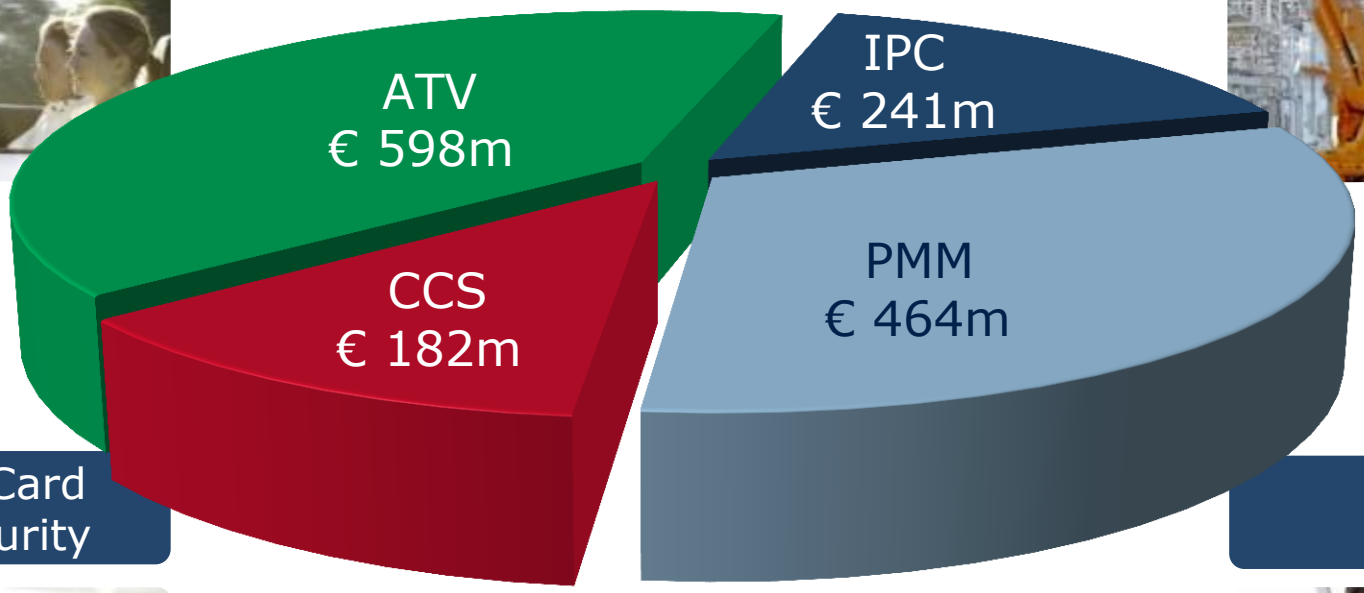
Revenue Split by Segment

Q2 FY 2015 Revenue: € 1,483m

Automotive

IPC



Chip Card & Security

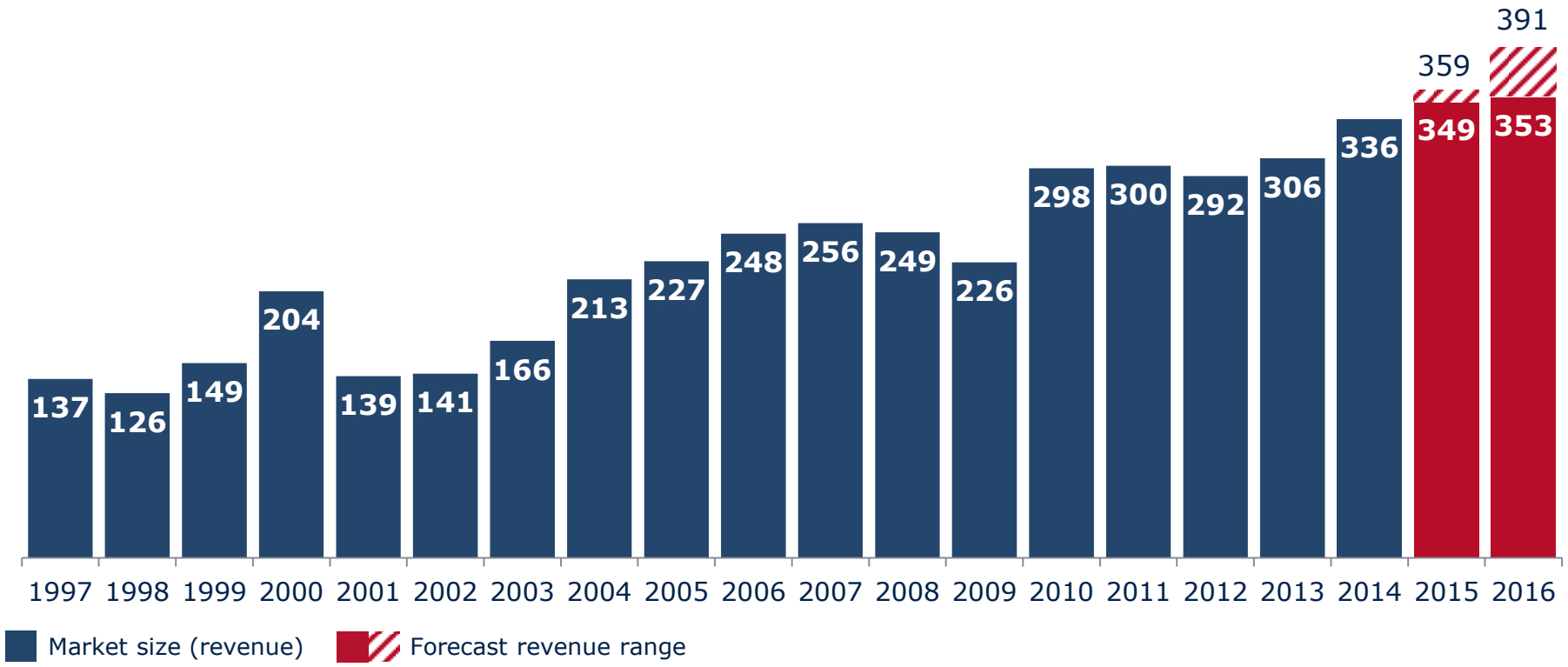
OOS+C&E*
€ -2m

PMM

*Other Operating Segments; Corporate & Eliminations.

Positive Growth Outlook for Global Semiconductor Market

Global Semiconductor Market
in Billion US-Dollar

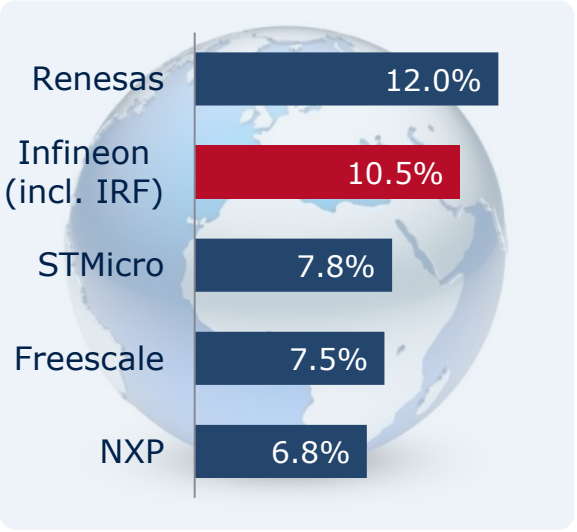


Source: WSTS for historical data. Forecast: ∅ of WSTS, IHS, Gartner, IC Insights; last update April 27, 2015

Infineon Holds Top Positions in All Major Product Categories

Automotive semiconductors

total market in 2014: $27.5bn

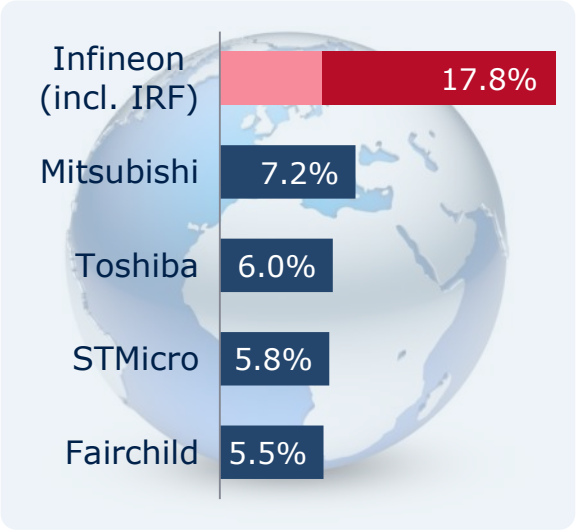


Automotive semiconductors incl. semiconductor sensors.

Source: Strategy Analytics, April 2015

Power semiconductors

total market in 2013: $15.4bn

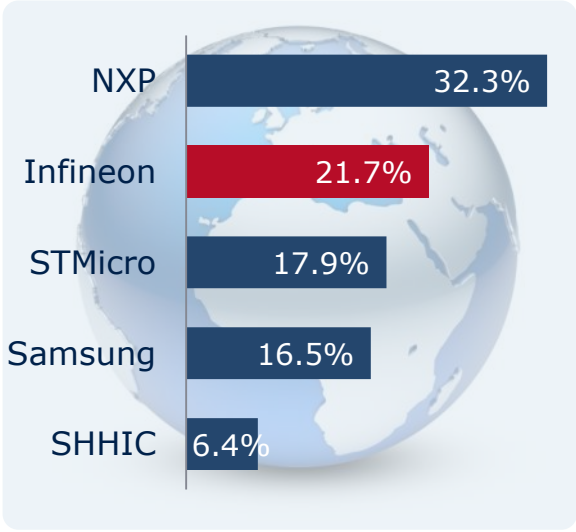


Discrete power semiconductors and power modules.

Source: IHS Inc., September 2014

Smart card ICs

total market in 2013: $2.48bn

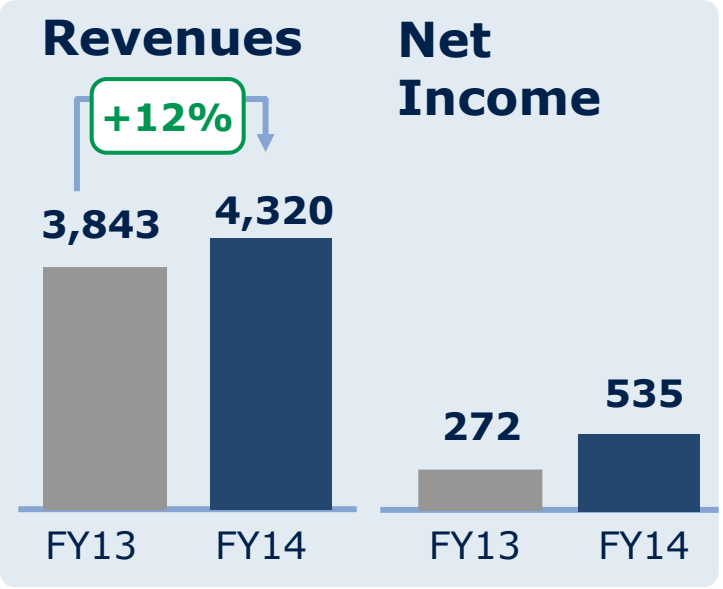


Microcontroller-based smart card ICs.

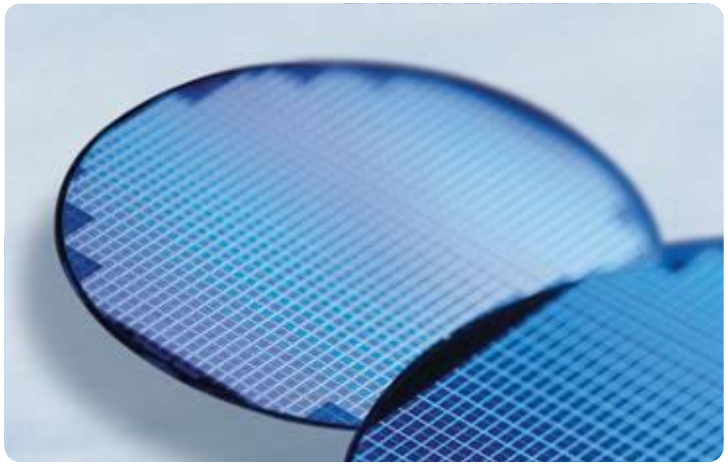
Source: IHS Inc., July 2014

Infineon Group
Results for FY 2013* and FY 2014*

*w/o International Rectifier



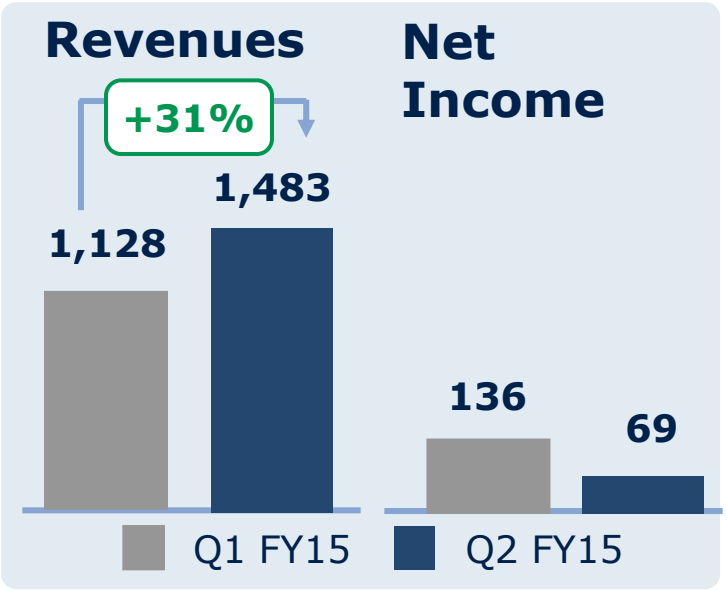
[€ Million]	2013	2014	
Revenues	3,843	4,320	↑
Segment Result (SR)	377	620	↑
SR Margin	9.8%	14.4%	↑
Net Income	272	535	↑



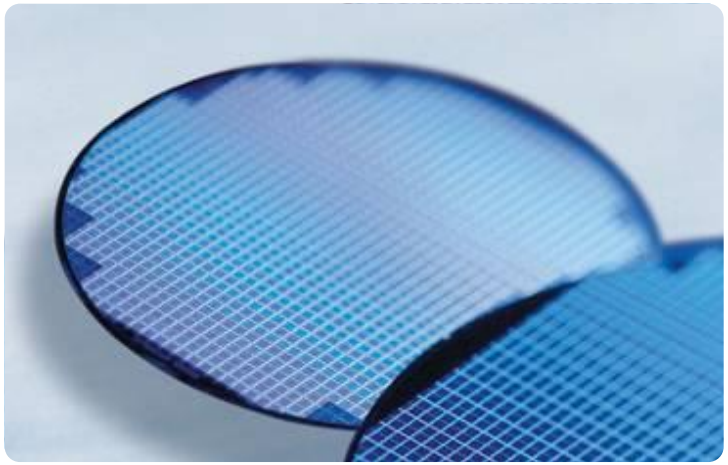
Free Cash Flow	235	317	↑
Investments	378	668	↑
Net Cash	1,983	2,232	↑
Market capitalization**	~7,995	~9,240	↑

**share price as of September 30th, 2013: 7.395 Euro; share price as of September 30th, 2014: 8.193 Euro

Infineon Group
Results for Q1 FY15* and Q2 FY15



[€ Million]	Q1 15*	Q2 15
Revenues	1,128	1,483
Segment Result (SR)	169	198
SR Margin	15.0%	13.4%
Net Income	136	69

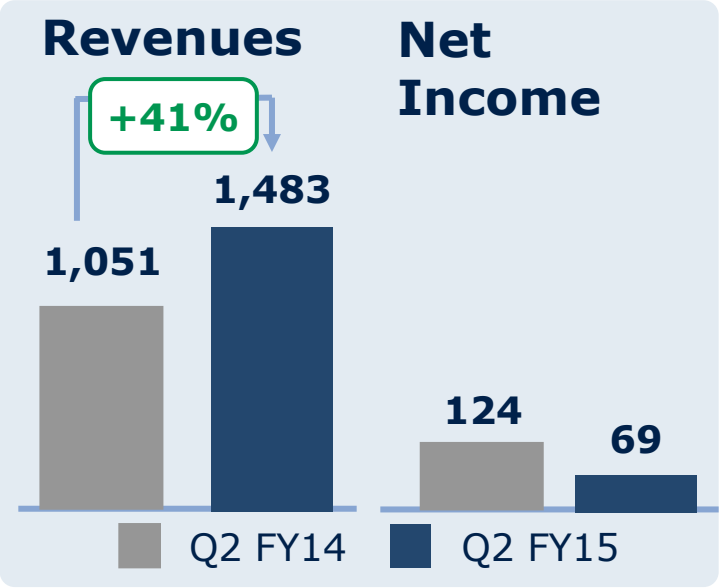


Free Cash Flow	(171)	(1,880)**
Gross Cash Position	2,107	1,656
Net Cash	1,917	(176)**

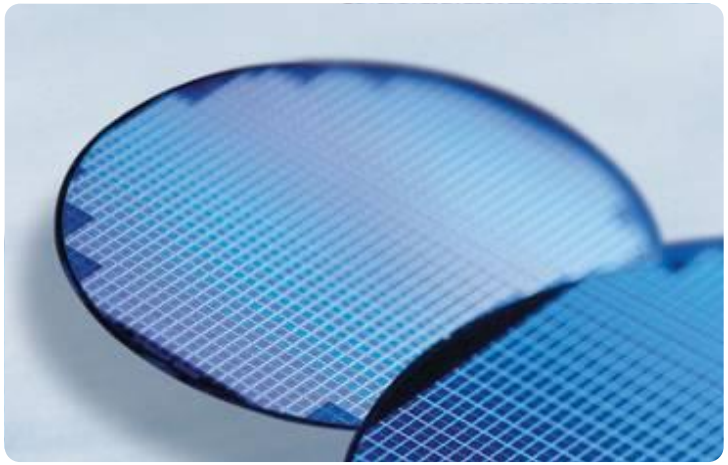
***w/o International Rectifier**

****includes transactions related to the acquisition of International Rectifier**

Infineon Group
Results for Q2 FY14* and Q2 FY15



[€ Million]	Q2 14*	Q2 15
Revenues	1,051	1,483
Segment Result (SR)	146	198
SR Margin	13.9%	13.4%
Net Income	124	69

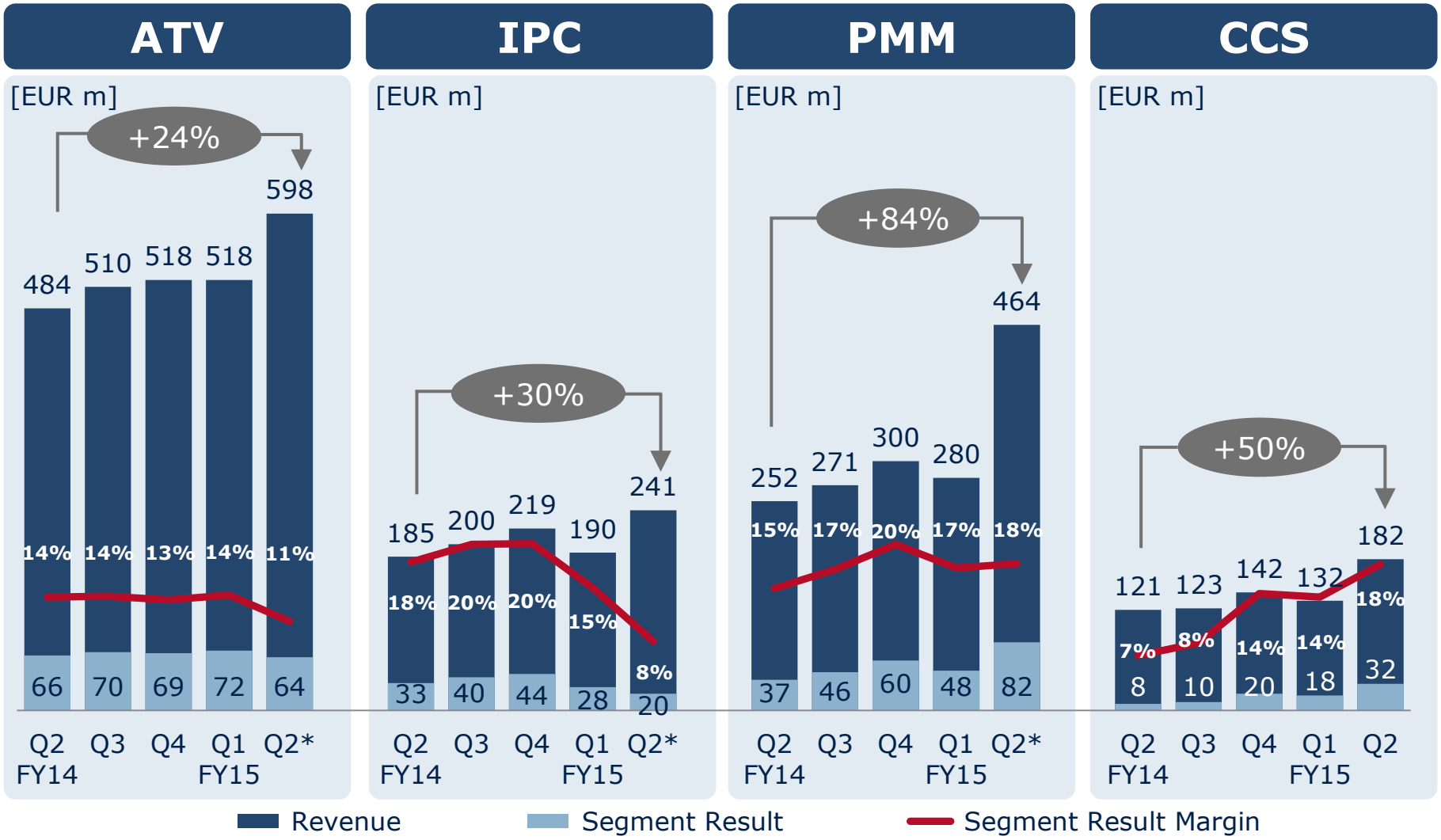


Free Cash Flow	51	(1,880)**
Gross Cash Position	2,198	1,656
Net Cash	2,010	(176)**

***w/o International Rectifier**

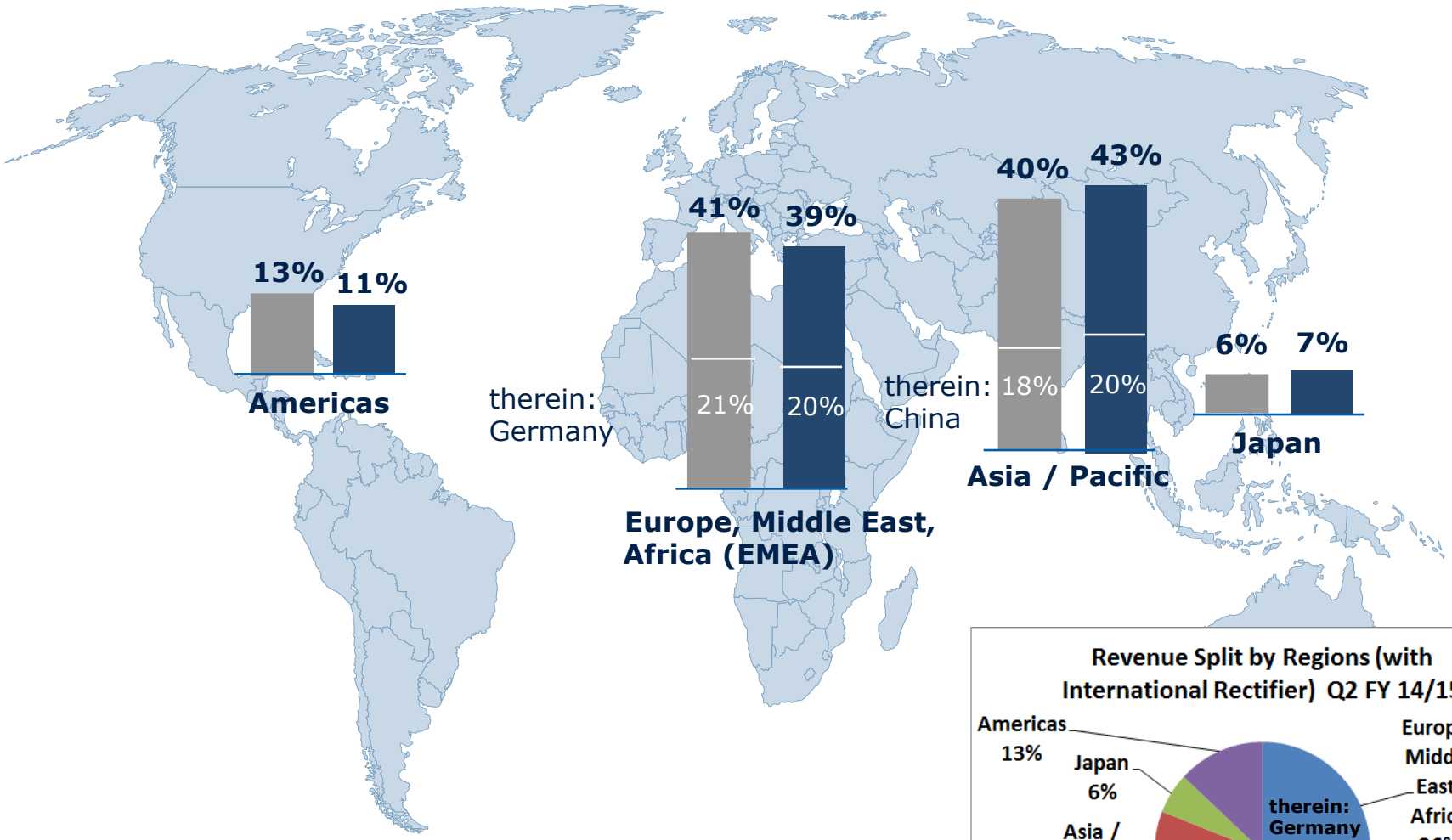
****includes transactions related to the acquisition of International Rectifier**

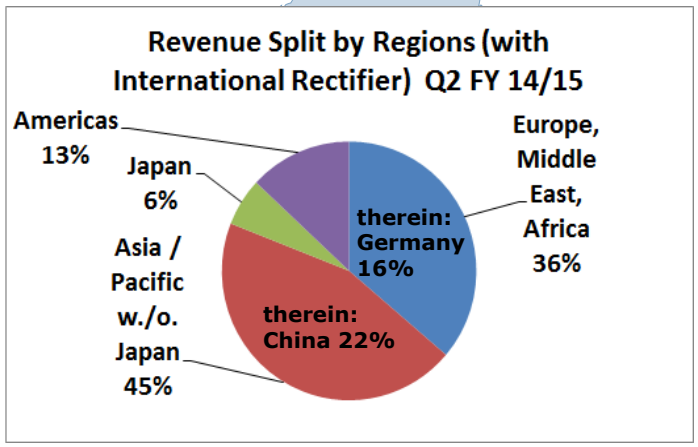
Segment Revenue, Result and Margin



* Including International Rectifier from 13 January to 31 March 2015.

Revenue Split by Regions FY 2013* and FY 2014*





FY 2013 FY 2014

***w/o International Rectifier**

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A Powerful Combination: Benefits of the Integration

Broader product portfolio

- Expansion of the product portfolio
- Broader and deeper under-standing of applications ("From Product to System" strategy)

Economies of scale

- Better cost structure thanks to broader sales base
- Faster ramp-up of production on 300 mm thin wafers

Greater technology expertise

- Broader GaN product and IP portfolio
- Faster roadmaps

Stronger presence in the regions

- Better regional presence in the U.S. and the Asia-Pacific region
- Expansion of market access via the distribution channel

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We Focus on Our Target Markets

Focus Areas

- Energy Efficiency
- Mobility
- Security

Core Competencies

- Analog/Mixed Signal
- Power
- Embedded Control
- Manufacturing Competence

Our Target Markets

- Automotive Electronics
- Industrial Electronics
- Information and Communications Technology
- Security

We Focus on Three Central Needs of Modern Society

Energy Efficiency | **Mobility** | **Security**

Automotive

Industrial Power Control

Power Management & Multimarket

Chip Card & Security

Energy Efficiency

Key Trends

- Soaring total energy demand across the globe amid dwindling fossil energy resources
- Strong CO_2 policies to achieve climate goals
- Tapping renewable energies as sustainable energy sources
- Electrification of the drivetrain of commercial and passenger vehicles

Our Contribution

- Infineon delivers semiconductor innovations playing a valuable role in minimizing power loss and maximizing power savings along the entire energy supply chain, extending from generation through distribution to actual consumption.
- Our products are the basis for intelligent and optimal use of energy resources in industrial, computing and consumer applications, and in cars.

Mobility

Key Trends

- Rigid CO_2 regulations and rising oil price
- Increasing rules on safety, focusing on preventive measures
- Rising new requirements in cars for emerging markets
- Urbanization, globalization and demographic change
- Strong investments in local and long distance public transportation systems

Our Contribution

- Leading semiconductor solutions contributing to a more sustainable mobility in terms of reduced fuel consumption/emissions, improved safety and affordability.
- As an innovation driver and supplier of key components for electric and hybrid vehicles, Infineon will actively help to shape the paradigm shift towards electro mobility on the road.
- Innovative public transportation solutions for traction and electronic tickets.

Security

Key Trends

- Secure communication everywhere utilizing mobile phone and internet
- Move to electronic identification of documents and products
- Contactless cards for payment and electronic tickets
- Increased intercommunication in cars, calling for secure data handling
- Introduction of smart grids calling for advanced data security

Our Contribution

- Tailored security according to system requirements, enabling the implementation of transparent security in everyday systems.
- Leverage our worldwide leadership in security know-how for smart cards in automotive and industrial applications increasingly demanding security.
- Combining both hardware security and cryptography, our products build the basis for privacy and security while maintaining personal freedom and facilitating extended communication capabilities.

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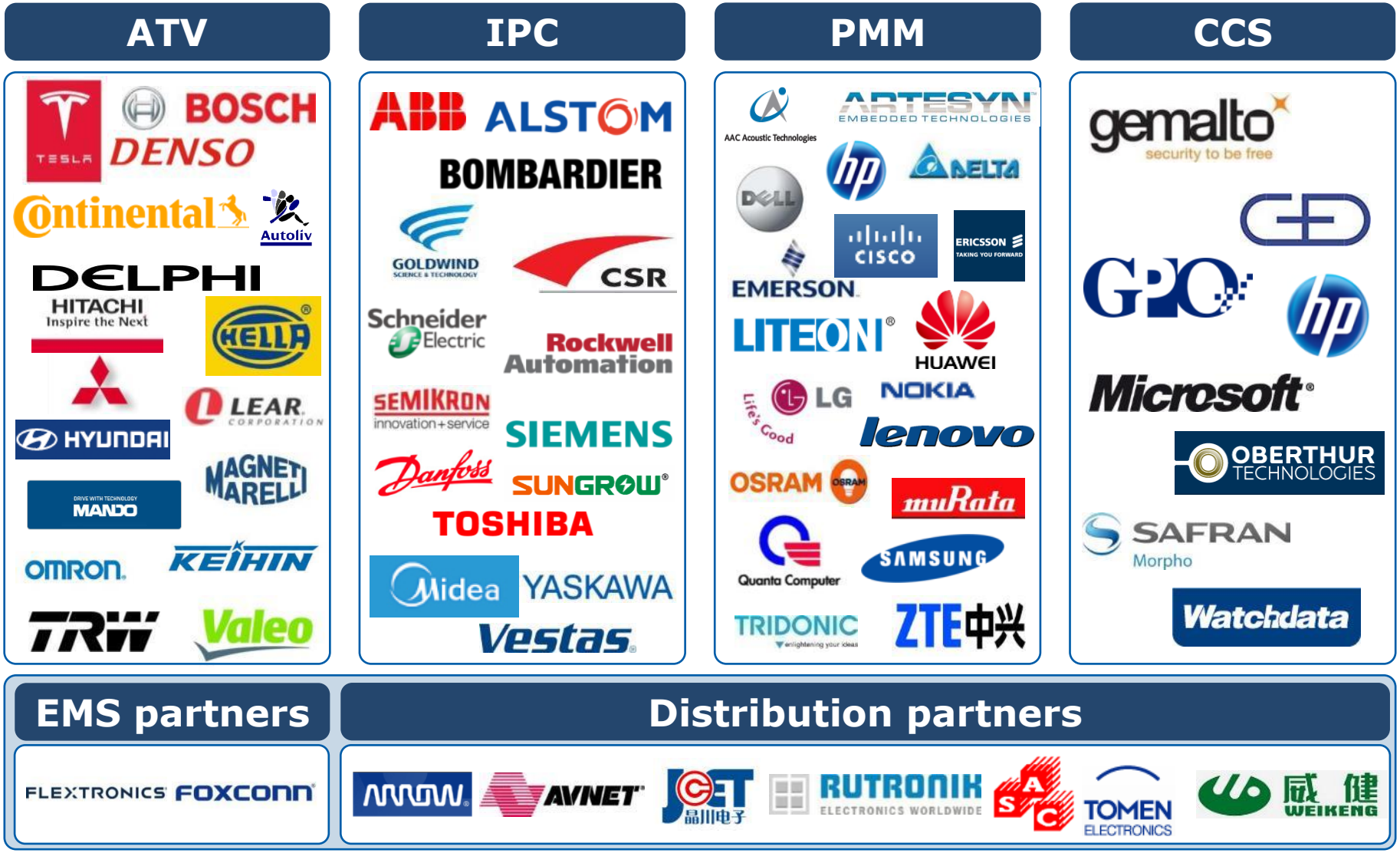
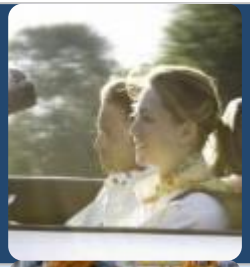
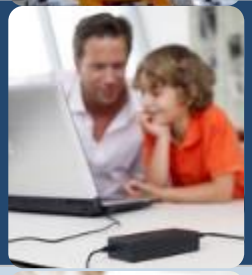
Tight Customer Relationships are Based on System Know-how and App Understanding



Market-Oriented Business Structure*

Segments		Applications
Automotive		Chassis and comfort electronics; Electric and hybrid vehicles; Powertrain; Safety; Security
Industrial Power Control		Charger station for electric vehicles; Energy transmission and conversion; Home appliances; Industrial drives; Industrial vehicles; Renewable energy generation; Traction; Uninterruptable power supplies
Power Management & Multimarket		Cellular network infrastructure; Light management and LED lighting systems; Micro inverters for photovoltaic rooftop systems; Mobile devices; Power supplies
Chip Card & Security		Authentication; Government Identification; healthcare cards; Mobile communication; Near Field Communication (NFC); Payment systems; Ticketing, access control; Trusted computing

Customers

*w/o International Rectifier

Product Range*

*w/o International Rectifier

Automotive (ATV)

- Microcontrollers (8-bit, 16-bit, 32-bit) for automotive and industrial applications
- Software development platform DAVE™
- Discrete power semiconductors
- IGBT modules
- Voltage regulators
- Power ICs
- Bus interface devices (CAN, LIN, FlexRay)
- Magnetic and pressure sensors
- Wireless transmit and receive ICs (RF, radar)

Industrial Power Control (IPC)

- IGBT module solutions incl. IGBT stacks
- IGBT modules (high-power, medium-power and low-power)
- Discrete IGBTs
- Bare die business
- Driver ICs

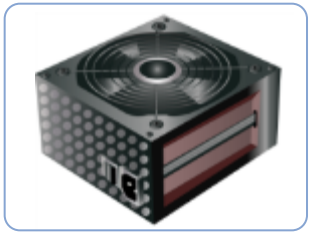
Power Management & Multimarket (PMM)

- Discrete high- and low-voltage power transistors
- Driver ICs
- Control ICs
- RF power transistors
- Small-signal components
- CMOS RF switches for antenna modules
- Antenna tuning ICs
- MEMS and ASICs for silicon microphones
- Customized chips (ASICs)

Chip Card & Security (CCS)

- Contact-based security controller
- Contactless security controller
- Dual-interface security controller (contact-based and contactless)

New Era:
Driving Demand for Power Semiconductors

'90 – '10	'10 – '30	Changes
	 Courtesy: BMW Group	■ Electrification in cars with Internal Combustion Engine as well as the trend towards emobility drives the demand for power semiconductors.
		■ Shift towards renewable energies requires significantly more high-power semiconductors per MW of power generated.
	 Courtesy: Facebook	■ Higher efficiency in power conversion reduces CO_2 emission and total cost of ownership.
		■ Stronger demand for goods containing power semiconductors due to increasing standard of living in BRIC countries.

Automotive Overview

Product Range

- **Sensors**: pressure, magnetic, radar
- **Microcontrollers**: 32-bit for Powertrain, Safety and ADAS
- **Power**: MOSFETs, IGBTs, smart power ICs: voltage regulators, bridges, driver ICs, CAN / LIN / FlexRay™ transceiver**, DC-DC converters, power system ICs, system-on chip, embedded power ICs
- **Hybrid & Electric Vehicle**: IGBT HybridPACK™, HybridPACK™ Double Sided Cooling (DSC) modules, gate driver ICs

Core Competencies/ Value Proposition

- **Automotive commitment**: More than **40 years** of automotive **system and application expertise**
- **Complete** automotive **system provider**
- **Hybrid and Electro mobility:** industry **leading expertise** and product portfolio
- **Functional Safety (ISO26262)** and **Security** enabling car solutions
- **Worldwide** development, production and support sites for automotive semiconductors
- **Next Level of Zero Defect**: most comprehensive quality program of the industry

Market Positions*

- **No. 2** in Automotive semiconductors worldwide
- **No. 1** Europe
- **No. 3** North America
- **No. 1** APAC & RoW
  - **No. 1** Korea
  - **No. 3** China
- **No. 4** Japan

- **No. 1 in automotive power semiconductors** (24.8%)

Source: Strategy Analytics (April 2015)

*incl. International Rectifier

**FlexRay is a trademark licensed by FlexRay Consortium GbR

We Focus on Future Trends Making Cars Clean

Market Trends

- Dwindling energy resources
- Urbanization
- Stricter CO_2 emission legislations
- Growing environmental awareness

Infineon's Opportunities

- Infineon components are key enabler for car manufacturers to meet challenging targets for CO2 emission reduction, e.g. in the EU 95g CO2/km in 2021
- We offer Hybrid and electric drivetrain products (HybridPACK™/HybridPACK™ DSC)
- No electric vehicle without semiconductors: electric drive and control, battery management, on-board battery charging and power grid communication

BMW and Infineon: Working Together to Shape the Future of Electro Mobility

Power module

- 75 semiconductors ensure a highly efficient electric drive in the BMW i3, e.g. Microcontroller AUDO Future, IGBT Power Module HybridPACK™ 2, EiceDRIVER™ Products, CoolMOS™ High voltage MOSFETs
- Further components: airbag control, LED light modules, steering locks, windshield wipers and seatbelt retractors

We Focus on Future Trends Making Cars Safe

Market trends

- Accident avoidance
- Autonomous driving
- Cyber-networked car

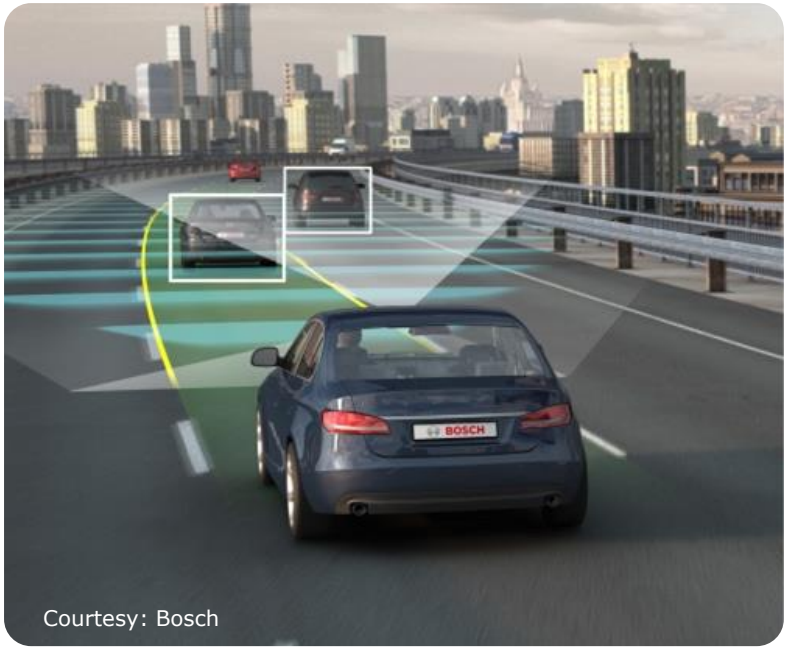
Key system requirements

- Reliability
- High Availability
- Functional Safety (ISO26262)
- Cybersecurity

Infineon's Opportunities

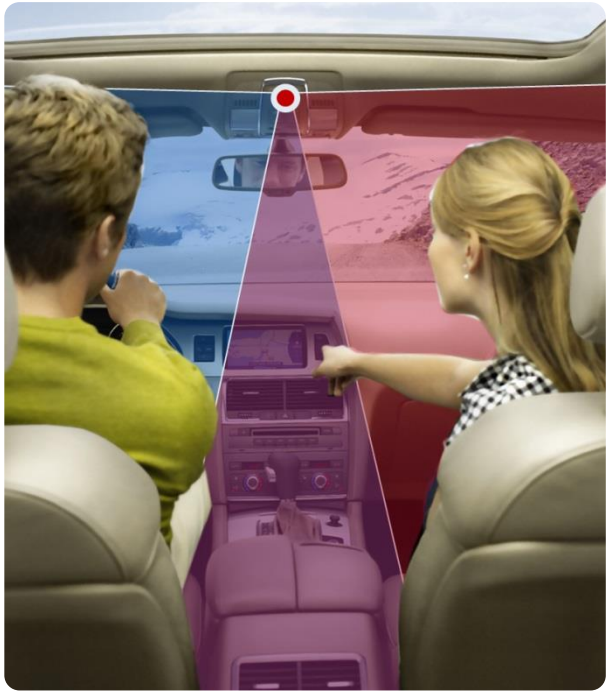
Infineon components covers the overall needs of the autonomous vehicle:

- AURIX™ microcontroller family enables dependable and secure processing
- Sensing technologies (e.g. Radar, Hall, 3D Imager) increase performance of ADAS systems
- Safe actuation solution (e.g. 3 phase Bridge Driver IC) and safe power supply enable dependable vehicle dynamics and control



Courtesy: Bosch

3D-Vision based Driver Monitoring: Increased Safety and enhanced Comfort



Active and passive Interaction

New ways of interaction due to autonomous driving and increased HMI (human machine interface) functionality:

- Occupant detection (position, size, weight,..) allows adaptive airbag activation
- Driver awareness monitoring to adjust intervention from ADAS systems
- Safety systems consider driver status, especially for autonomous driving
- Touchless gesture control allows intuitive, fast and less distractive interaction

Infineon's 3D Image Sensors

- 3D cameras based on the Time-of-Flight (TOF) principle with active infrared illumination provide optimum performance
- Simplified object segmentation (less calculation effort and independent from object colors, patterns and textures)
- Very small form factor of TOF-cameras due to monocular design

Courtesy: KOSTAL

Industrial Power Control Overview

Product Range

- **IGBT Modules:** Standard IGBT Modules, Power Integrated Modules (PIM) and Converter Inverter Brake (CIB) Modules
- **IPM Modules:** molded Intelligent Power Module (IPM)
- **Discrete IGBTs**
- **Driver ICs:** standalone driver IC products for combination with IGBT modules and discretes
- **Power Stacks:** Power module assemblies including heat sink, Driver IC and protective sensors/functions, etc.

Core Competencies/ Value Proposition

- High quality products and services
- Leading edge technology and IP portfolio
- System expertise with broad application competence
- Strong worldwide presence with local sales and application support
- Dedicated account teams and distributors

Market Positions*

- No.1 in Discrete IGBTs with 24.7% market share
- No.2 in IGBT modules with 20.5% market share
- No.2 in IGBT semiconductor products (module & discretes) worldwide
  - No.1 in Europe
  - No.1 in China

*Source: IHS Research, September 2014, without International Rectifier

Power Components for Drive Control of Train Systems

High-Speed Trains

Metro Trains

Infineon Parts

- Power: 5 to 10MW per train
- 80 to 120 IGBT modules per train
- Semiconductor content: ~ € 100,000 per train

- Power: 0.5 to 1MW per train
- 25 to 50 IGBT modules per train
- Semiconductor content: ~ € 10,000 per train

Power Components for Wind Converters and HVDC connection of Offshore Parks

Onshore/Offshore Wind

HVDC connection of Offshore Park

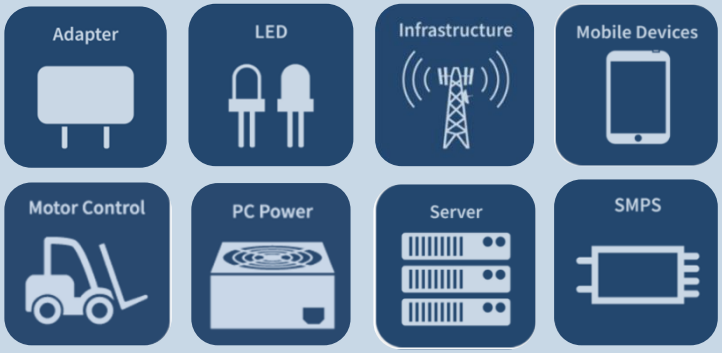
Infineon Parts

- Power: 1MW to 6MW per turbine
- 12 to 48 IGBT modules **or** 6 to 12 Power Stacks per turbine
- Semiconductor content: ~ € 5,000 per MW

- Power depends on amount of connected offshore parks
- 4,000 to 16,000 modules per connection
- Semiconductor content: ~ € 5,300 per MW

HVDC: High Voltage Direct Current

Power Management & Multimarket Overview



Product Range

- AC/DC and DC/DC Digital Control and Driver ICs
- High, Medium and Low Voltage Power Discretes
- RF Switches, Low Noise Amplifier, TVS Diodes, GPS Modules, RF Power
- Silicon Microphone, Dig. ASICs, Pressure Sensors, Radar IC
- ASIC design solutions for authentication and battery management
- GaN Class D Audio Amplifier
- HiRel Discretes & Modules

Core Competencies/Value Proposition

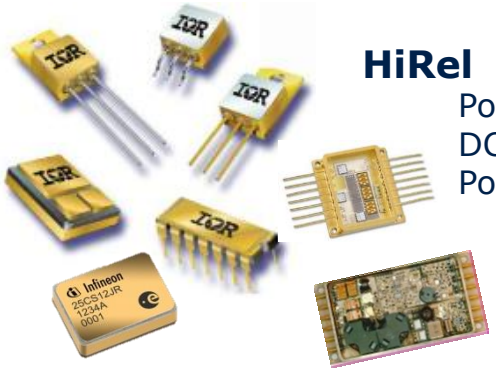
- Technology Leadership in Power & RF:
  - Energy Efficiency
  - Power Density, system size and weight reduction
  - Connectivity and reliable, clean Data Transmission for 50bn devices in 2020
- Revolutionary Innovation made "easy to use"
  - Application centric Innovation
  - Integration competence: Power/RF, Digital Power, Modules/MMIC/Discretes, chip embedding
- System understanding drives more efficient power management

Market Positions*

- **No. 1 Power Semiconductors 18%** market share (IHS: The World Market for Power Semiconductor Discretes & Modules – Sep. 2014)
- **No. 1 in Discrete Standard MOSFETS 25.6%** market share (IHS: The World Market for Power Semiconductor Discretes & Modules – Sep. 2014)
- **No. 2 in Chips for Silicon Microphones with 30%** market share (IHS: MEMS Microphones Report– April 2014)
- **No. 3 in RF Power Devices with 15 %** market share (ABI Research: RF Power Amplifiers – March 2014)

*with International Rectifier

PMM Product Overview



HiRel
Power Discretes
DC/DC Converters
Power Modules

High Voltage MOSFET
CoolMOS™

Silicon Carbide
SiC Schottky Diodes

PMM

Power Systems, HiRel Connectivity & Sensing

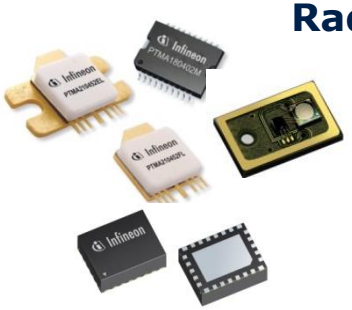
AC/DC IC
Dig. Power Controllers
Driver IC
Lighting IC

GaN

Sensors
Silicon Microphone
Dig. ASICs
Pressure Sensors
Radar IC

Low & Medium Voltage MOSFET
OptiMOS™, DirectFET™,
StrongIRFET ™

Radio Frequency
RF Switches
GPS Module
LNAs
RF Power



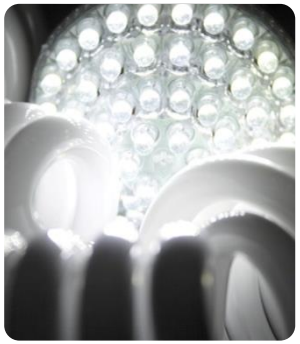
DC/DC Single- & Multi-Phase IC
Dig. Power Controllers
Power Stages
Driver ICs
Synchr. Rec IC
Integrated PoL
Class D Audio

Power Components for Servers and RF Devices Cellular Communication and Infrastructure

Power Management

Computing

Lighting



Charger

Mobile Communications

Mobile Devices

Cellular Infrastructure

Portfolio: MOSFETs, Power ICs, RF Switches, LNAs, Si-Mics, TVS Diodes, RF Power

- Efficiency values of 95% and higher
- Technology leadership in silicon and silicon carbide products
- Highest power density enabling best cost-performance ratios
- Unique system solutions with MOSFETs, power ICs and driver products

- Silicon Microphone sensor element with leading edge acoustic, electrical and quality performance
- Excellent performance in ESD protection
- Best-in Class Noise Figure in Low Noise Amplifier

- Applicable for all standard frequencies of 2G, 3G, 4G (450 MHz to 2.7 GHz)
- Industry leading power efficiency for LTE
- Wide range of devices with power levels from 4–700 W
- Best-in-Class thermal performance

Social Networks and Cloud Computing Driving Demand for Highest Efficient Power Supplies

Digital Power Management (DPM) Gaining Traction in Server Market

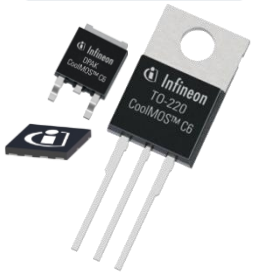
amazon.com Google

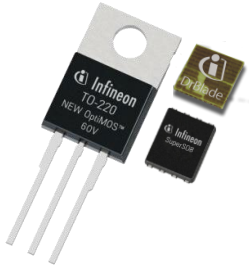
Picasa

Microsoft YouTube

- Globally, we see one new data center per week with up to 100 MW of power consumption
- Efficiency of power supply (AC/DC, DC/DC) of utmost importance.
- DPM best solution for flexible load dynamics
- Change in value chain: servers no longer from the shelf but designed by ODMs according to specification of data center operator

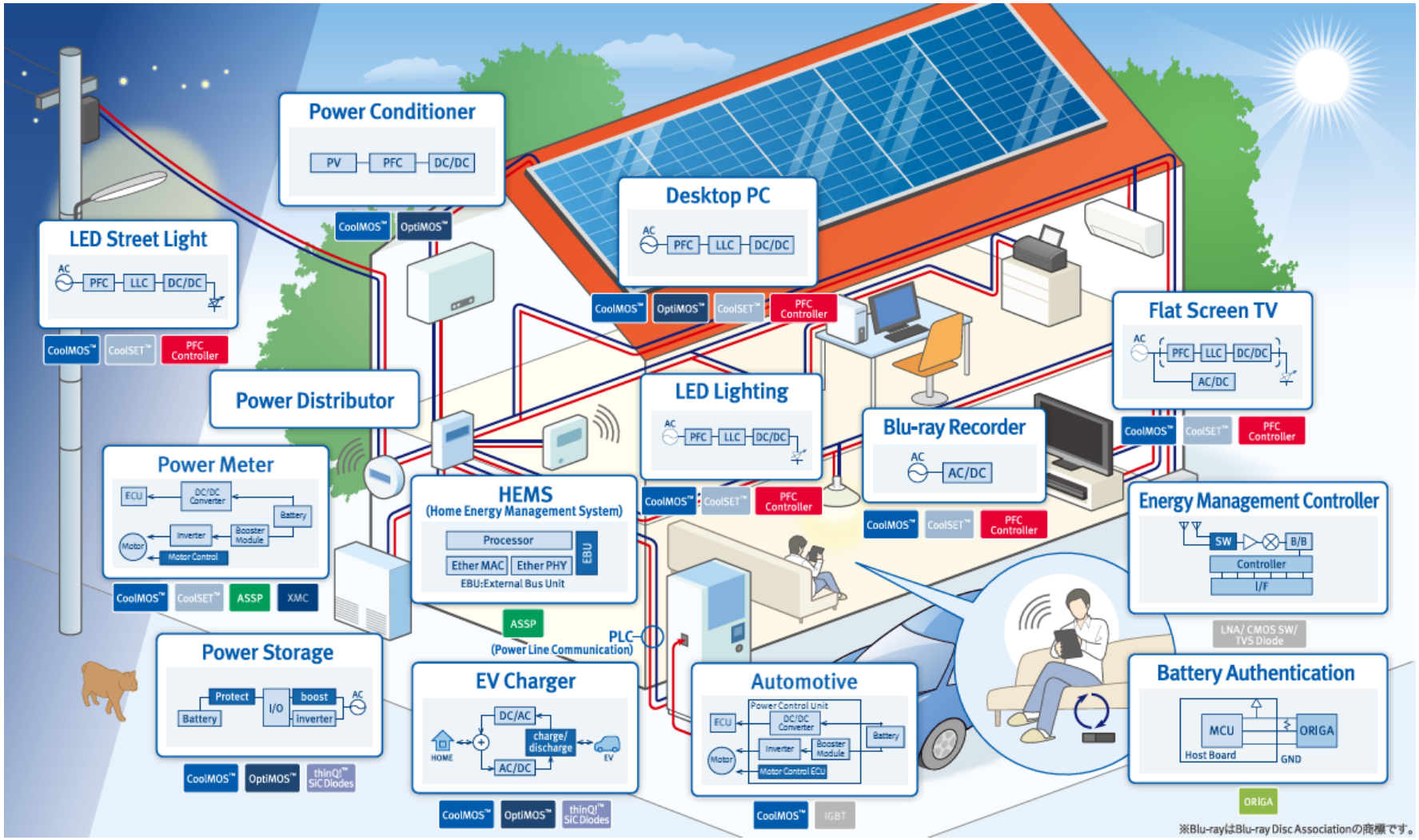
CoolMOS™ | OptiMOS™ | Controller & Driver IC





- DPM opens the door for bundling with other products
- Recent design win: Infineon offers DPM controllers along with driver ICs and MOSFETs to Taiwanese ODM

Power Semiconductors: Solutions for Efficient Energy Use



Chip Card & Security Overview

Product range

- Contactless and contact-based security products for Communication, Payment, Mobile Security, Internet of Things (IoT) Security, Government Identification, Transport, Access, Object Identification, and Entertainment
- Innovative solutions from basic security RFID and memories to high-end security controllers (including the award winning SLE 78 family)
- Extensive packaging and service portfolio

Core competencies & value proposition

- **Tailored security**

  Right level of security at the best cost-performance ratio
- **Contactless excellence**

  Focus on interoperability and dual interface
- **Embedded control**

  Right trade-off between computing power, power consumption, level of security and cost

Market positions

- No. 2 in Microcontroller Smart Card ICs with 21,7%[1] market share in CY2013* by revenue
- No. 1 in TPM; leading positions in Authentication ICs and Mobile Security ICs (secure elements in devices and on SIM cards)
- No. 2 in SIM card IC with 19%[2] market share in CY2013 in terms of volume
- No. 2 in Payment with 28%[3] market share in CY2013
- No. 2 in Government Identification with 32%[4] market share in CY2013

Source: [1,4]IHS, July 2014; [2]ABI, August 2014; [3]May, Sep2014 IHS; IFX internal *Calendar year

Infineon supplies embedded secure element chips to Samsung's Galaxy S6 and S6 edge

Infineon Embedded Secure Element Chip for Samsung Galaxy S6 and S6 edge

- Infineon supplies the embedded Secure Element (eSE) chip for **Samsung's new premium smartphones Galaxy S6 and S6 edge**
- Samsung's flagship Galaxy's S6 and S6 edge mobile devices use the **Infineon SLE 97 eSE**
- Infineon's SLE 97 is a SOLID FLASH™-based eSE chip which can **safeguard the functionalities of the mobile device as well as transactions** where users' sensitive data such as payment credentials are concerned

Infineon supplies security controllers to Microsoft's Surface Pro 3 tablets

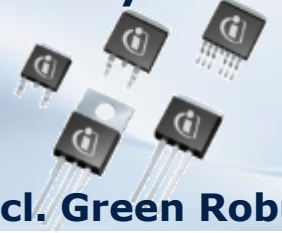
Infineon Trusted Mobile Platform (TPM 2.0) for Microsoft Surface Pro 3

- Infineon's OPTIGA™ TPM (Trusted Platform **Module) security controller is used in Microsoft's Surface Pro 3**
- Microsoft's Surface Pro 3, widely recognized for its excellent performance both as a tablet and a laptop replacement, utilizes the higher security and improved system management features of the **latest TPM 2.0 standard**
- The Infineon OPTIGA TPM SLB 9665 series is used in Surface Pro 3 - supporting a wide range of security needs ranging from **strong authentication** to **platform integrity checks**

Semiconductor Technology Portfolio

Technology portfolio fits needs of logic and power applications

Power/Analog



incl. Green Robust

Analog Bipolar: DOPL, A*x*, BIPEP, B4CD
Analog BiCMOS: B6CA, B6CA-CT, B7CA, SPT170 HV-CMOS-SOI, Levelshift(SOI,JI)
Smart Power: 1200-130nm BIP/CMOS/DMOS SPT*x* (Automotive, EDP) (BCD)
Smart: CMOS/DMOS, SMART*x*, MSMART*x*, SSMART*x*, Opto-TRIAC, SPS

DMOS: 12-500V Planar and Trench MOSFET (OptiMOS™,HEXFET™)
HV-DMOS: Superjunction MOSFET (CoolMOS™)
IGBT: Planar & Trench 500-6500V, rev. cond., fast recov. diodes
SiC/GaN: Diode, JFET / power switches

adopted for automotive, industrial and for high reliability requirements

MEMS/Sensors

Magnetic: B*x*CAS, C9FLRN_GMR

Opto: OP-DI, OP-TR, OP-C9N, µ-modules C11TOF

Pressure: B*x*CSP, TIREP*x*

Silicon-Microphones: DSOUND

CMOS

Digital CMOS: 800nm – 65nmTechnology Nodes (Platform <180nm incl. RF, AMS)
Analog/Mixed Signal: 500nm – 180nm Technology Nodes (C*x*NA)
eNVM: EEPROM: IMEMR, C9FL, OTP: C5OP (Automotive)
eFlash/EEPROM: 250nm – 65nm C*x*FL (Chip Card), C*x*FLA, C*x*FLN (Automotive)
HV-CMOS: 130nm, C11HV

RF/Bipolar

RF BiCMOS: 25GHz – 100GHz: B6HFC, B9COPT, B10C
Bipolar IC: 2GHz...200GHz RF-Bipolar: B*x*HF
HiPAC: Al/Cu Integrated Passives P7M*xx*, P7D*xx*, P8M*xx*

SiGe: B7HFM, B7HF_SLC, B7HF200
RF Switches: C7NP, C11NP

Bipolar/Discretes/MMIC:
RF-Transistors NF-TR; BxHF(D/M),
Power Amplifier: LDMOS, LD*x*M, LD*x*IC, LD9AB
Diodes: NF-DI, Tuner: D*x*T, Schottky: D*x*S

SiGe: B7HFD/M, B7HF_SD
RFMOS: HFM
PIN: D*x*P

Package Technology Portfolio

IC

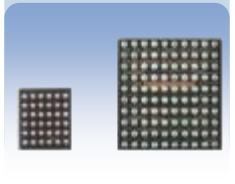
Wafer Level Packages, Bare Die

Surface Mount Technology (SMD)

Wafer Level
w/o redistribution
- WLP (fan-in)

w/redistribution
- WLB (fan-in)
- eWLB (fan-out)
- Blade

Bare Die
- Wirebond
- Flip chip



Laminate based Packages

SMD
- OCCN 1,2)
- BGA
- LBGA
- xFBGA, xFSGA

Leadframe based Packages

Through Hole
- DIP 2)

SMD
- PLCC 2)
- TSSOP
- TQFP
- LQFP
- MQFP

Leadless
- VQFN
- WQFN
- O-LQFN 1)
- XSON
- USON

Chip Card

Mold on LF
- P-MCCx

Mold
- P-Mx.x

Chip on Flex
- FTM

UV Globe top
- T-Mx.x

PRELAM
- PPxx

Flip Chip
- S-MFCx.x
- S-COMx.x

Wafer
- Bumped
- Diced

Discretes

SMD leaded
- SOT
- SOD
- TSOP
- TSSOP

Flat lead
- TSFP
- SC

Leadless
- TSLP
- TSSLP
- TSNP

Wafer level
- WLP
- WLL

Sensors

Through Hole
- PSSO

SMD Leaded
- DSOSP

Open cavity
- DSOF

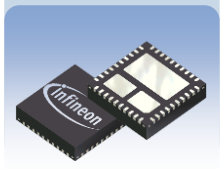
Power

Power

Through Hole
- TO, DIP

SMD
- TO
- DSO
- SSOP

Leadless
- ThinPAK
- TDSON
- TSDSON
- DirectFET™
- TISON
- WISON
- IQFN
- HSOF



Power Modules

High Power
- Easy
- 34mm
- 62mm
- Econo
- Econo-PACK™+
- Prime-PACK™
- IHM
- IHV
- Hybrid-PACK™

Intelligent Power Modules
- IRAM
- CIPOS™
- µIPM™

1) for specialities only 2) phase-out

Table of Contents

Decisive Competitive Advantage: Quality at Infineon

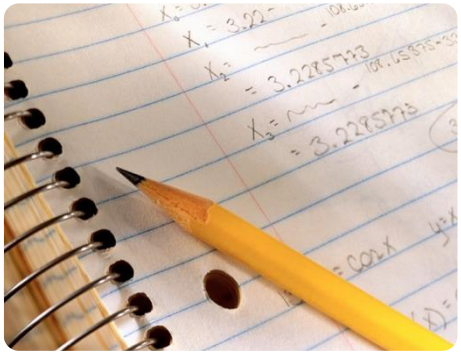
Our aspiration

- Preferred partner for our customers
- Smooth production and delivery
- We focus on stability and the 100 percent fulfillment of our commitments

Our path

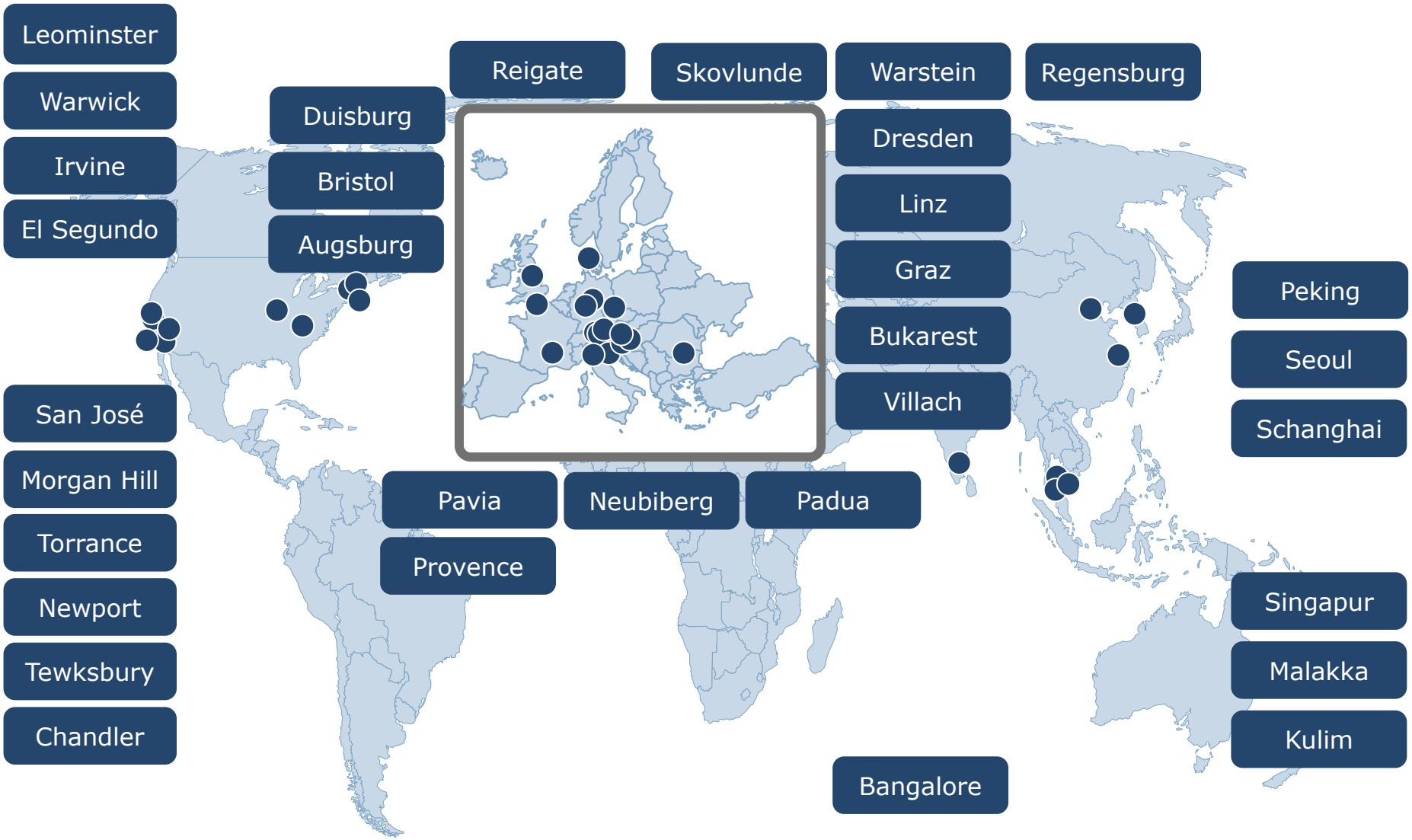
- Integrated approach along the entire value chain
- Proactive Quality Management for products and processes

Our standards



- International Standards, e.g. TS16949, ISO 9001, IEC 17025
- Specific customer requirements

Our global R&D network



Worldwide Manufacturing Sites Frontend and Backend

Our global Sales network

Corporate Social Responsibility*
Our Commitment

United Nations Global Compact
10 Principles

Human Rights

Principle 1: support and respect the protection of internationally proclaimed human rights

Principle 2: make sure they are not complicit in human rights abuses

Labor

Principle 3: uphold the freedom of association and the effective recognition of the right to collective bargaining

Principle 4: uphold the elimination of all forms of forced and compulsory labor

Principle 5: uphold the effective abolition of child labor

Principle 6: uphold the elimination of discrimination in respect of employment and occupation

Environment

Principle 7: support a precautionary approach to environmental challenges

Principle 8: undertake initiatives to promote greater environmental responsibility

Principle 9: encourage the development and diffusion of environmentally friendly technologies

Anti-Corruption

Principle 10: work against corruption in all its forms, including extortion and bribery

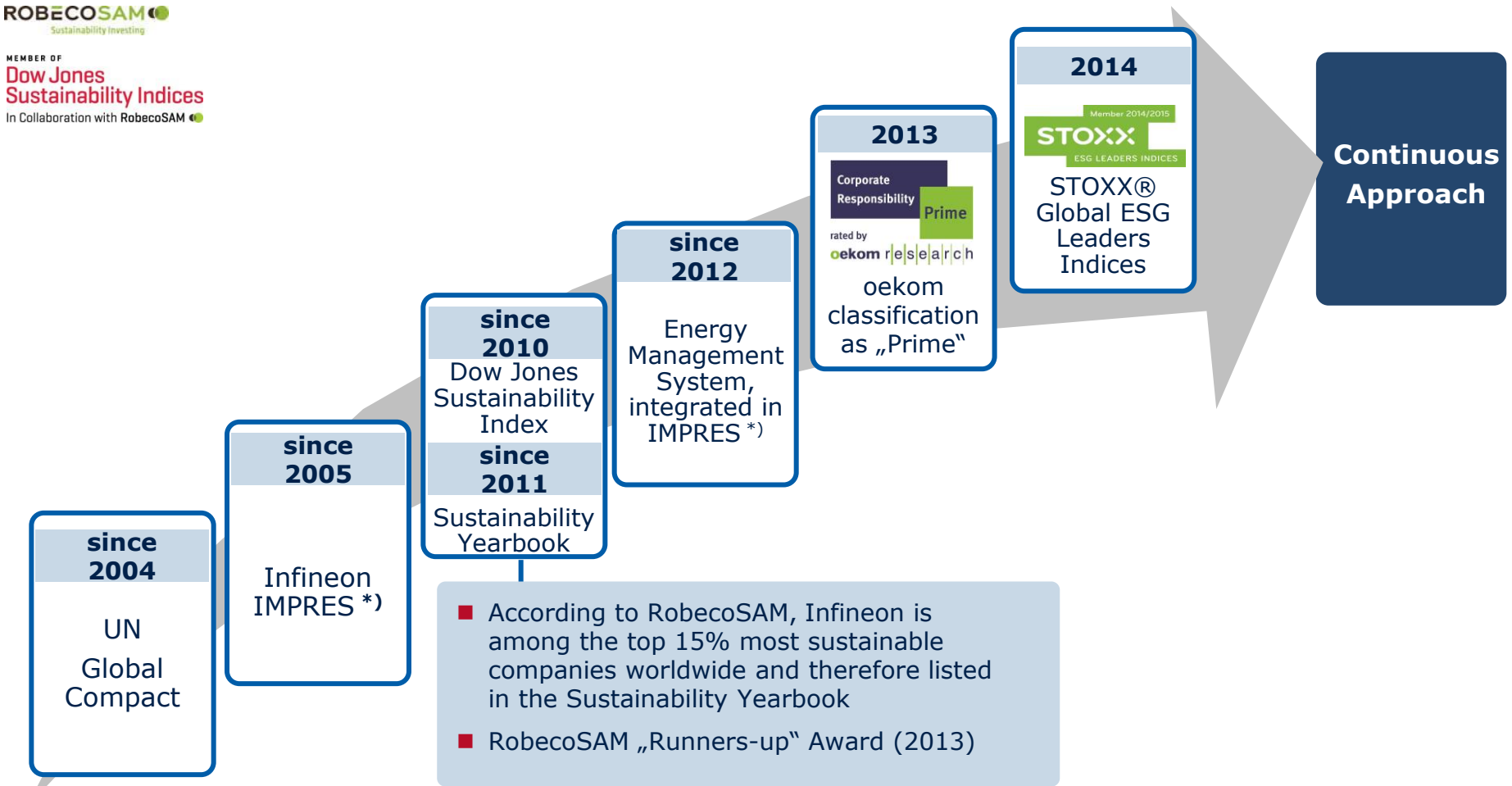
*w/o International Rectifier

Corporate Social Responsibility*
Our Understanding

CSR at Infineon comprises our voluntary commitment and contributions in the areas:

*w/o International Rectifier

Corporate Social Responsibility*
Successful CSR Approach



*w/o International Rectifier

Corporate Social Responsibility
We apply certified Management Systems

Environmental sustainability is not only our business – it is our commitment

- Our integrated management system for environmental protection, energy, occupational safety and health is third party certified.

DNV·GL

MANAGEMENT SYSTEM CERTIFICATE

Certificate No.: 131538-2013-AE-GER-DAkkS | Initial date: 14.02.2013 | Valid: 01.02.2015 - 31.01.2018

This is to certify that the management system of

Infineon

Infineon Technologies AG

Am Campeon 1-12, 85579 Neubiberg - Germany
and the sites as mentioned in the Appendix (page 1 to 2)
accompanying this Certificate

has been found to conform to management system standards:

ISO 14001:2004, ISO 50001:2011,
BS OHSAS 18001:2007

This certificate is valid for the following Scope:

Development, production and sales of semiconductor components

Place and date: **Essen, 01.02.2015**

For the Issuing Office: **DNV GL Business Assurance Zertifizierung und Umweltgutachter GmbH**

DAkkS Deutsche Akkreditierungsstelle D-ZM-18458-01-00

Thomas Beck
Technical Manager

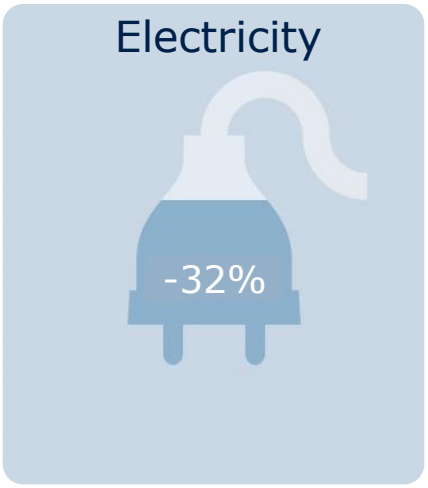
Lack of fulfilment of conditions as set out in the Certification Agreement may render this Certificate invalid.
ACCREDITED UNIT: DNV GL Business Assurance Zertifizierung und Umweltgutachter GmbH, Schnieringshof 14, 45329 Essen, Germany.
Tel.: +49 201 7296 222. www.dnvgl.de/assurance

* ISO 50001 in EU sites

The information and data given in this document apply to the Infineon Technologies group, except for International Rectifier companies.

Corporate Social Responsibility
We are excellent in Resources Efficiency

At Infineon, less is more



About **32% less** electricity consumed per square centimeter produced wafer than the global average

About **20% less** water consumed per square centimeter produced wafer than the global average

About **47% less** waste generated per square centimeter produced wafer than the global average

We use resources much more efficient in our production processes than the global average of the semiconductor industry.

Basis for the calculations are the square centimeters processed wafer area in the front-end production and consumptions according to WSC definition.
The information and data given in this document apply to the Infineon Technologies group, except for International Rectifier companies.

Our CO_2 Footprint: Emissions Reduction Enabled by Our Products and Solutions*

*w/o International Rectifier

1.4 million tons

CO_2 burden[1)]

Ratio 1:10

More than 14.4 million tons

CO_2 savings[2)]

Net ecological benefit*:
round 13 million tons of CO2 emission reduction

1) This figure considers manufacturing, transportation, function cars, flights, materials, chemicals, waste/waste water, direct emissions, energy consumption, waste, etc. and is based on internally collected data and externally available conversion factors. All data relates to the 2014 fiscal year.*
2) This figure is based on internally established criteria, which are explained in the explanatory notes. The figure relates to the calendar year 2013 and considers the following fields of application: automotive; lamp ballast control; PC power supply; renewable energy (wind, photovoltaic); and rives. CO_2 savings are calculated on the basis of potential savings of technologies in which semiconductors are used. The CO_2 savings are allocated on the basis of Infineon's market share, semiconductor content and lifetime of the technologies concerned, based on internal and external experts' estimations. Despite CO_2 footprint calculations are subject to imprecision due to the complex issues involved, the results are nevertheless clear.*

Business Continuity
Integrated Management*

*w/o International Rectifier

ENERGY EFFICIENCY
MOBILITY
SECURITY

Innovative semiconductor solutions for energy efficiency, mobility and security.